Vanadium Dioxide for Reconfigurable Antennas and Microwave Devices

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We present a comprehensive study of a new method to reconfigure, tune, and/or program antennas and radio-frequency (RF) devices. The method consists of using electrical signals to induce the solid-to-solid phase transition in vanadium dioxide (VO₂) thin-film patterned structures that connect the device metallization layer with extensions, thus effectively changing the geometry of the device. Applied voltage pulses to a resistive heater electrically isolated from the antenna metallization layers increase the temperature of the VO₂ strip across the phase transition. Hence, the VO₂-biasing mechanism and the antenna are electrically decoupled, which enables an additional degree of freedom for antenna and microwave device engineers as the reconfiguration is no longer restricted by any biasing network limitations. Radiation patterns are also maintained unaffected. This decoupling adds into the design spectrum, applications that require wideband tuning, low-loss structures (e.g., arrays and reflectarrays), and even reconfigurable cloaks. The VO₂ switch is arguably the smallest ever used to reconfigure an antenna, which requires further circuit element considerations. The presented method is validated through a series of antenna prototypes that demonstrate VO₂ applicability on wire and aperture antennas. Details and challenges of the monolithic integration of VO₂ thin films and resistive heaters for reconfigurable antennas, along with the measurement setup, are presented. Results unveil this new reconfiguration technique and suggest further applications, as the VO₂ may also be activated optically.

INTRODUCTION

The phase transition of a material occurs under certain stimuli and affects the material molecular structure. An example of a common material that changes phase is water, which becomes solid, liquid, or gas at different temperatures. Interestingly, the relative dielectric permittivity of water also changes, from \( \varepsilon_r = 80 \) at its liquid state, to \( \varepsilon_r = 3.2 \) when solid, while its volume increases by 5%.

VO₂ is a phase-change material, first reported in 1959 [1], that undergoes an insulator-to-semiconductor transition when subjected to a variety of stimuli. During the transition, VO₂ exhibits orders of magnitude of change in electrical resistivity (\( \rho \)) and relative dielectric permittivity (\( \varepsilon_r \)), referred to as insulator-to-metal transition (IMT). Although VO₂ has been used in terahertz applications [2], [3], there have been very few reported antenna prototypes in the gigahertz range. This article reports results from the first exploration of the hypothesis that VO₂ can be used in reconfigurable and tunable RF devices.
The VO₂ transition occurs through various methods: conductive heating [4], Joule heating [5], using photothermal techniques [6], voltage biasing [7], and ultrafast optical excitation [8]. This work explores how convective heating and resistive heating can provide significant advantages for reconfigurable antennas and RF component applications. Traditionally, reconfigurable antennas employ electrically connected components, such as RF microelectromechanical systems (MEMS) [9]–[13], positive-intrinsic-negative (p-i-n) diodes [14], varactors [15], and field-effect transistors (FETs) [16] that are also nonlinear in nature. However, these components also demonstrate limitations in RF performance in terms of efficiency, power handling, and frequency tunability imposed by their biasing circuitry, while their integration or soldering can reduce device reliability and robustness. As an example, the FET transistor biasing network [16] shown in Figure 1 has also been used in many tunable antenna and filter designs [17]–[19]. The network limits the tuning range to about 20% or less, which is the bandwidth of the quarter-wave open-circuited stub with the quarter-wave line. Moreover, the FET transistors had to be placed near the ends of the slot at low impedance points to prevent mismatch and field changes, which imposed additional limitations on the design flexibility and thus affected the available tunable bandwidth. In another example [16], the same biasing network reconfigures a coupled lines filter at six different states, achieving a 15% tuning range.

Wideband biasing matching networks require multiple components that increase design complexity, cost, and losses. The presented technology eliminates the need for λ/4 stubs, small capacitors, and inductors that require soldering. This can prove valuable for antenna engineers. The fact that the activation mechanisms are resistive heaters that do not touch the RF/radiating structure make the VO₂ technology very advantageous.

There have also been some notable recent advances related to VO₂. Researchers investigated thermal triggering of VO₂ RF switches on tin oxide (SnO₂) and titanium oxide (TiO₂) substrates achieving more than 15-dB change in insertion loss [20]. Also, in another interesting work, Yang et al. reported an inkjet-printed VO₂ RF switch with 40-μs actuation that operates at 40 GHz and has a two orders-of-magnitude ON/OFF response [21]. Further insights into the IMT transition process were presented in [22].

However, until recently no articles in the literature discussed the bandwidth limitations of the reconfigurable antennas. These limitations motivated investigations of alternative methods to achieve reconfigurability for antenna designs. Here we show how the relatively new technology of phase-change materials can overcome bandwidth limitations by decoupling the bias network from the design, and how it can lead to larger reconfigurable structures with low loss.

The most important characteristic of the VO₂ switch is that its phase change can be actuated without electrically connecting a biasing circuit to the antenna. This characteristic can be particularly useful for antenna designers as it allows the antenna to be reconfigurable without the complexities associated with the integration of MEMS or with the soldering of passive or active off-the-shelf components. This additional degree of freedom can be obtained by integrating resistive heaters underneath the VO₂ thin films. The resistive heaters are electrically biased, but they are not electrically connected to the antenna structure or to the VO₂ thin film. The phase change is enabled through heat transfer from the heater to the VO₂ film through the material. Without any electrical coupling, the only form of coupling that can affect the design is the mutual coupling between the VO₂ films and the bias lines. These lines, however, are thin and can be designed so that their electric-field (E-field) vector near the antenna surface is perpendicular (cross-polarized) to the antenna, which practically eliminates any field disturbance due to coupling.

**VO₂ PHYSICS AND MODELING**

Phase transitions, which usually occur as a function of temperature and pressure, are commonly observed as changes between the four states of matter: solid, liquid, gas, and plasma. There are, however, other types of phase transformation where for both phases the material remains a solid. Graphite and diamonds are examples of solids made of the same elements but with significant differences in their properties due to a different atom orientation or crystal structure. In these cases, going from one phase to the other involves specific combinations of high pressures and temperatures. However, there are a few solid–solid phase-change materials that only require a change in temperature, E-field, carrier injection, or ultrafast optical radiation to induce a change in the crystal orientation that comes with drastic changes in the material properties [23]. Among these types of phase-change materials, VO₂ has the phase change that is closest to room temperature, happening at about 68 °C [23].

**THE BEHAVIOR AND PHYSICS OF VO₂**

The first-order phase transformation in VO₂ comes with an abrupt change in the electrical, mechanical, and optical...
VO₂ is a nonmagnetic material, hence, its relative magnetic permeability \( \mu_r \) is one. From an engineering perspective, the IMT of the VO₂ changes its \( \rho \) and its \( \varepsilon_r \) by three to four orders of magnitude.

The abrupt changes in the properties of VO₂ make it a viable candidate for its implementation in electronic, mechanical, and optical applications. Furthermore, the fact that VO₂ is the solid–solid phase-change material with the activation temperature closest to room temperature makes it the ideal candidate for real applications where power consumption is a parameter of interest.

The hysteresis in VO₂ brings a memory capability that has been used in multiple devices for programming electrical, mechanical, and optical states [4], [25]. Thus, VO₂ is a smart multifunctional material that provides abrupt and completely reversible changes in multiple properties with a relatively low stimulus and allows for the programming of these properties.

**DIELECTRIC PERMITTIVITY**

Reported results demonstrate that the relative dielectric permittivity properties of the material \( \varepsilon_r \) change across the phase transition. Specifically, \( \varepsilon_r \) varies from a value near 36 at room temperature to more than 10,000 when the VO₂ is heated, as shown also in Figure 3 [26].

The shift of the dielectric permittivity value can be disregarded in simulations at the heated state due to the conduction effects overpowering the capacitive ones. It is thought that with the RF current traveling through the material during the heated state, the increase in permittivity would have little to no effect on the results.

However, in the cooled state of the VO₂, the relatively high permittivity value requires the thickness of the VO₂ and of the adjacent metal layers to be considered in the simulations. This is because there is a capacitive well created along the VO₂ patches, as explained later in the “Fabrication” section. The capacitance of the well can be found by the thickness of each substrate across the VO₂ walls that form the well. For completeness, the equivalent circuit for the VO₂ switch is illustrated in the “VO₂ for Microwave Circuits” section and is similar to others reported in series and in coplanar waveguide connections [20], [27], [28].
RESISTIVITY

The change in VO$_2$ resistivity across its phase transition is largely dependent on its stoichiometry, grain size, and crystallinity. When depositing VO$_2$ thin films, all of these parameters are strongly dependent on the substrate. For example, VO$_2$ thin films grown over quartz or sapphire have larger resistivity drops across the phase transition than VO$_2$ thin films grown over amorphous or crystalline silicon. The extremes of this shift are dependent on what substrate the VO$_2$ is deposited on, and the overall variance can exceed four orders of magnitude.

The resistance variation of the VO$_2$ was measured across a 400-nm-thick polycrystalline VO$_2$ thin film deposited over C-cut sapphire (the same substrate structure used for the folded aperture antennas presented in the section “VO$_2$ for Reconfigurable Aperture Antennas—Coplanar Folded-Slot Antennas”). The resistance results are shown in Figure 4 for a full temperature cycle. A four orders-of-magnitude decrease in the resistance is observed when the VO$_2$ is heated.

The impedance–temperature relation of the patterned VO$_2$ film was also measured with respect to frequency to better understand how to use the material properties in frequency-dependent applications, such as antennas. The impedance of the VO$_2$ thin strip integrated on a VO$_2$ antenna was measured using an Agilent 8753ES S-Parameter Network Analyzer for every 2 °C from 30 to 100 °C and from 100 to 30 °C. The frequency range for these measurements was from 30 kHz to 6 GHz. The setup, shown in Figure 5(a), probed the metal adjacent to the VO$_2$ strip. Using the measured data, a graph for the measured impedance was made. As expected, the impedance decreased dramatically with temperature, particularly above 68 °C, featuring also a gradual decline as frequency increased. This decline is due to the thin VO$_2$ layer sandwiched between two thicker metallic layers that effectively create a structural well that acts as a planar-integrated capacitor. This hypothesis was validated by electromagnetic simulations where the thickness of all metal layers was considered, leading to better accuracy. The obtained data validated also the reactive behavior (energy storage and slightly reduced gain) observed on the first reported VO$_2$ antenna, the bowtie described in the section “VO$_2$ for Reconfigurable Wire Antennas—Bowtie Antennas.”

**VO$_2$ MODELING**

The patches of VO$_2$ in this article are approximated as thin-film resistors and are modeled as such. Using method-of-moments software, such as Advanced Design System (ADS) by Keysight and IE3D by Zeland Software, a separate metal class was created and labeled as a thin-film resistor so that the material could then be directly incorporated in the antenna.
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geometry. To model each state of the VO₂, heated and cooled, the resistance material property in ohms per square (Ω/□) was altered. Measurements across square VO₂ patches determined that the values of 300 and 6 kΩ/□ are relatively accurate values for modeling the cooled and heated VO₂ states respectively for the specific fabrication technique that would be used. Due to the complex nature of VO₂, a combination of potential small variations in the thickness and stoichiometry of the material can result in large differences in patch resistance, and the material patches may not have identical electrical properties. The values were found to be sufficiently accurate, through a trial-and-error process in which fabricated wafers and antennas were measured and characterized, for use in modeling the material on a sapphire substrate.

The resistance (Ω/□) simulation values allow for the patch design process to be reduced to a simple matter of adding resistors in series and in parallel. This allows for the calculation of a specifically defined VO₂ patch. Equation (1) can be applied to find the required number of parallel squares that result in a desired resistance, in which X is the number of squares, R is the desired resistance, and Rs is the Ω/□ value:

\[
\left( \frac{X}{R_s} \right) = R.
\]  

This approach defines the width-to-length dimensions ratio required to obtain a specific resistance. For example, if 10 Ω is needed, (1) yields X = 600 squares. As long as the width of the material patch is 600 times larger than its length, the resistance of that patch will always be 10 Ω.

Although the measured resistance values are large, when used in an antenna structure, a parallel connection of many squares reduces the total resistance to acceptable values. Smaller resistance values have been reported in the literature [30, 31], leading to series and slant RF switches with less than 2.2- and 0.9-dB insertion loss respectively [30], with the most common technique to reduce the resistance being the deposition of a thicker VO₂ layer. Moreover, resistive and resistively loaded antennas [e.g., antennas for ground-penetrating radars (GPRs)] that have specific profiles can take advantage of this resistance. Examples include resistive bowties, resistively loaded antennas [such as with the Wu–King profile [32], [33] in Figure 6(b) or conducting wires of increasing resistance [34] for reduced late-time ringing in GPRs [35]], and many others [36]–[45].

**VO₂ FOR MICROWAVE CIRCUITS**

Prototypes of microwave-frequency circuits (RF switches, RF power limiters, and phase shifters) that employ VO₂ are briefly presented next to better comprehend the VO₂ capabilities and frontiers. In [30] researchers implemented a thermally triggered VO₂ RF switch [Figure 7(b)]. In the series configuration, VO₂ acts as an open circuit below 68 °C and does not allow the RF current to pass through. When heated, VO₂ resistance drops dramatically and it allows RF current to pass through with low loss.

In [46], a power limiter was developed. It is composed of series-connected power divider/combiners with VO₂ shunts. Each resistive load, when activated, absorbs a percentage of the input power. The loads are in series to divide the transmitted power that enters in each stage of the limiter.

In [31], researchers implemented a low-loss 2-bit 50-GHz phase shifter by forming two VO₂ SP4T switches [Figure 8(b)]. The switches enable different paths of the phase shifter with electrical delay in multiples of 90°. Low losses were achieved by depositing a thicker layer of VO₂ (600 nm). The high linearity validated the use of VO₂ for wideband applications.

**VO₂ FOR RECONFIGURABLE ANTENNAS**

Designing a reconfigurable antenna involves altering the geometry of the structure. VO₂ has been proven capable of controlling the current flow, so two antenna prototypes, namely a planar bowtie and a folded-slot, were designed to test the effectiveness of VO₂ as a catalyst for antenna reconfigurability. The designs are based on different operating principles (bowtie as a wire antenna [47] and folded slot as an aperture) to study the application of the VO₂ on two representative classes of antennas. Also, the bowtie allows the activation of the VO₂ to result in a decrease of its resonant frequency, while the folded slot allows for it to be increased.

![FIGURE 6. Examples of VO₂ applicability on resistively loaded antennas. (a) Metal bowties typically have increased ringing in the time domain. (b) Resistive and VO₂-loaded bowties with a Wu–King profile or wires of increasing resistance have reduced ringing and are more suitable for late-time ringing in GPRs [35]. (c) Capacitive-loaded or traveling-wave antennas [34]. PEC: perfect electric conductor.](image)
Each antenna was fabricated and measured, as shown later in the article. All $S_{11}$ measurements were taken with the antenna placed in the anechoic chamber and are compared to simulations. Pattern measurements were taken to investigate any effect of the VO$_2$ on the pattern shape. Additional measurements were taken to ensure that the directive heat source, required to activate the transition of the material, did not influence the data.

**VO$_2$ FOR RECONFIGURABLE WIRE ANTENNAS—BOWTIE ANTENNAS**

The first proof-of-concept antenna using VO$_2$ as the catalyst for reconfigurability is a bowtie design on sapphire that is fed using a coaxial sleeve balun. The VO$_2$ enables frequency reconfigurability by extending the length of each antenna arm symmetrically. This is achieved by depositing two 200-nm thin films of VO$_2$ that physically establish the connection between the two separate sections of each arm, thus enabling the two operation states. This antenna was presented in [47] and is not repeated herein. Table 1 shows the dimensions of the prototype shown in Figures 9 and 10.

The antenna was fabricated, as per the process outlined in [47], on a sapphire substrate ($\varepsilon_r = 11.5$, $\tan\delta = 0.0001$, thickness $t = 0.558$ mm), using the following steps:

1) deposition of a VO$_2$ thin film by pulsed-laser deposition in a 15-mTorr low-pressure chamber with controlled O$_2$ flow of 20 standard cm$^3$/min for 25 min
2) patterning by reactive ion etching (RIE) to create the two thin strips that will extend the metallization sections of the antenna
3) precise gold (Au)-layer electroplating and multiple photore sist spins.

Results indicate that the antenna indeed shifts frequency when the VO$_2$ undergoes a thermally induced phase change. The radiation patterns [47] were similar at both frequencies as expected. At the cooled state, the

![FIGURE 7](image)

![FIGURE 8](image)

![TABLE 1](image)
measured gain was 0.14 dBi with the heated state giving −0.67 dBi. As expected, the 0.8-dB gain reduction of the heated antenna was due to loss (heat) from the current passing through the VO₂, but most losses are attributed to the introduced capacitance due to the thin and narrow VO₂ film deposited adjacent to the thicker metal arms, resulting in power being stored within the antenna near field. This is due to the advantage of the VO₂ switches being extremely small (i.e., 20 μm in length). Notably, this series capacitance can be minimized by depositing a thicker and larger layer of VO₂ at the cost of having a slower switch. The thicker VO₂ will also have lower resistivity. In the future, this can enable the use of VO₂ at higher frequencies (up to several terahertz) where the metallization layers can have thickness in the order of the VO₂ layer. For the fabricated antenna, however, the calculated efficiency is 41% (heated) and 49% (cooled).

Further investigation requires the study of a reconfigurable aperture type of antenna. It is also necessary this time to demonstrate at least 25% frequency reconfigurability. A slot or folded-slot aperture antenna allows such an investigation. In these antennas, the aperture field is created by the surrounding current. The VO₂ reduces the aperture circumference by creating short circuits on it. These short circuits increase the resonant frequency. The folded-slot design has a more stable input reactance, which allows for good matching without feed modifications, and so it was preferred.

The radiating frequency of a folded-slot aperture antenna can be defined by its parameter C, which directly relates to the perimeter of the slot defined by

$$\frac{C}{\lambda_0} = \frac{C_0}{\sqrt{(\varepsilon_r + 1)/2}}$$

(2)

where C₀ is the value of C/λ₀ when ε_r = 1. Here, C = 2 × ((L₁ + b + W_a + W_b), and ε_r is the permittivity of the substrate. C₀ can be computed numerically (e.g., for L₁/b = 0.019, C/λ₀ = 0.93), and physically it compensates for fields outside the aperture.

Reconfigurability is enabled by adding two metallic extensions on each side of the aperture, without metallic islands (see Figure 11). Each extension pair is joined together with a narrow film of VO₂. The thin strips of VO₂ adjoin the metal pathways and elongate or shorten the perimeter and thereby decrease or increase, respectively, the frequency. The layout and operating principle of this type of antenna are shown in Figure 11.

When unheated, the VO₂ acts as an open circuit, and the current is forced to move along the perimeter of the aperture, which establishes the lower frequency of
operation. When VO₂ is heated, resistance drops to a value in which the current chooses the inner pathway establishing the higher frequency.

A major difference between the incorporation of the VO₂ in the presented prototypes is that the coplanar folded-slot antenna has a much lower resistance requirement for its heated state. To enable reconfigurability and minimize ohmic losses, the width-to-length ratio of the VO₂ film can be large. Here, the length is 4 μm with the width of 1.3 mm (total number of squares: 325), which made the VO₂ resistance 18 Ω when hot and 920 Ω when cold. The 200-nm-thick layer of VO₂ was printed on a 0.558-mm-thick aluminum oxide (Al₂O₃) substrate with εᵣ = 11.5 and was matched to a 75-Ω transmission line (see dimensions in Table 2).

The simulated surface current confirmed the operating principle of the antenna (Figure 12). Simulated results showed a large frequency shift from 4.27 to 6.53 GHz, a shift of 52.9%, which exceeded the targeted 25%. This antenna was fabricated using the same process as that for the previous prototype. Figure 13 shows a photo of the fabricated device.

The measured |S₁₁| (in Figure 14) shows a frequency shift from 4.125 to 7.1 GHz, or about 73.1%. This is equivalent to the shift achieved with MEMS that use resistive bias lines, yet the VO₂ switch is planar and more robust as it has no mechanical moving parts.

An additional comparison of the radiation patterns (Figure 15) showed good agreement as well, validating the modeling of the VO₂. The gain of the antenna in the cooled state was measured to be 1.73 dBi (calculated efficiency: 68%) with the heated state at 1.65 dBi (calculated efficiency: 64.5%). Again, the efficiency of the antenna was 4% lower at the heated state as there is again some energy stored in the capacitive well. The losses due to the VO₂ were calculated to be approximately 5.5%. To mitigate these losses, it is necessary to reduce the losses (resistance) of the heated VO₂, thus enabling longer switches with larger capacitive wells. Such low resistance values have been reported in the literature [25], [30]. The VO₂ in this prototype is very narrow (only 4-μm wide), which is arguably the shortest integrated antenna switch ever made.

In Figure 14, the cooled simulated resonance is shifted higher than the measured resonance, while the heated simulated resonance is shifted lower. In the heated state, the measured resonance was at a higher frequency than the simulated resonance due to the pin on the SMA connector feeding the antenna farther down the transmission line. Also, the wavelength is different for each frequency, so the feed does not affect all states the same. At the cooled state, the measured resonance is slightly lower than the simulated resonance due to the added capacitance from the high εᵣ of the VO₂, which causes current to travel farther down the inner paths before continuing around the perimeter of the slot. Further interaction with the thick SMA connector may also have affected the current path.

**VO₂ INTEGRATED ANTENNA WITH RESISTIVE HEATERS**

The previous two antenna prototypes validated VO₂ as a suitable material for wire and aperture types of reconfigurable antennas. The VO₂ on these antennas was activated using a convective directive heat source placed 10 cm from the antenna surface. The heater activated the transition of the material in an average of 14 s without overheating the cables. However, this heat source can be bulky and heavy. Practical commercial and defense applications often require effortless integrated actuation of the VO₂ with transition times in the range of microseconds.

### TABLE 2. DIMENSIONS FOR THE APERTURE ANTENNA.

<table>
<thead>
<tr>
<th>Dimension</th>
<th>W_a</th>
<th>W_b</th>
<th>W_p</th>
<th>W_s</th>
<th>L_s_hot</th>
<th>L_s_cold</th>
<th>L_c_hot</th>
<th>a</th>
<th>g</th>
<th>b</th>
</tr>
</thead>
<tbody>
<tr>
<td>Value (mm)</td>
<td>6.85</td>
<td>6.55</td>
<td>1.3</td>
<td>0.004</td>
<td>2.75</td>
<td>11</td>
<td>16.2</td>
<td>7.5</td>
<td>2.5</td>
<td>0.3</td>
</tr>
</tbody>
</table>

![Figure 12](image12.png)

**FIGURE 12:** The simulated surface current flowing (a) around the full aperture when the VO₂ is unheated and (b) around the smaller aperture through the VO₂ patches when the VO₂ is heated.

![Figure 13](image13.png)

**FIGURE 13:** A fabricated VO₂ folded-slot antenna. The 4-μm VO₂ line appears faint and is barely visible in the inset photo.
To reduce the transition time, Joule heating [5] was investigated through the use of integrated resistive heaters. A video that shows the change in color of a VO₂ thin-film patch when current passes through an underlying resistive heater is available [48]. A new antenna was then designed, this time with four integrated resistive heaters, to 1) demonstrate and validate the successful integration and 2) to extract useful conclusions through the added complexity of the device having the biasing lines of the resistive heaters. Both the heaters and the bias lines are integrated within the substrate of the antenna and are not electrically connected to any part of the antenna structure, which is a major achievement in the sense as these bias lines do not interfere with the antenna.

**DESIGN**

The antenna design that was used is a coplanar folded-slot antenna with a smaller aperture to address X-band applications. This design incorporates four VO₂ thin-film patches placed at the edges of each metal strip, as shown in Figure 16. Under each VO₂ film is a silicon dioxide (SiO₂) isolation layer, and under that layer a platinum (Pt)-resistive heater is deposited along with the dc bias lines that extend underneath the antenna, as shown in Figure 17. As the dc lines pass largely underneath the ground layer of the antenna, while most fields are concentrated in the aperture area, the interference of the lines with the antenna impedance and pattern's shape is negligible. All dimensions are in Table 3. Simulated results for the antenna showed that frequency reconfigurability is achieved with the two resonant frequencies being at 9 GHz (cold VO₂) and 11 GHz (hot VO₂).

**FABRICATION**

The fabrication process for the antennas with dc bias (see Figure 18) started with the deposition and patterning of resistive heaters and insulating SiO₂ film. A sapphire (Al₂O₃) wafer (5.08 cm in diameter and 558-μm thick) was used as a starting substrate. The resistive heaters and dc bias lines were defined by using standard metal liftoff of a Ti/Pt layer (50/150 nm). It is necessary to use a high-temperature metal (e.g., Pt) for the dc bias lines and resistive heater, since the deposition of VO₂ occurs at approximately 470 °C. After the dc bias and resistive heaters have been defined, a layer of SiO₂ (1 μm) was deposited over the entire surface. This layer is necessary to electrically isolate the VO₂ film (next film deposition) from the resistive lines. After the deposition of the dc bias lines, resistive heaters, and insulating SiO₂ layer, the steps of the fabrication process for both types of antennas was very similar. The next step in the process is the deposition of the VO₂ thin film.

**FIGURE 14.** The measured and simulated |S₁₁| of the VO₂ folded-slot antenna.

**FIGURE 15.** The measured radiation patterns of the VO₂ folded-slot antenna. Solid lines: copolarization; dashed lines: cross polarization. (a) E-plane, unheated. (b) E-plane, heated. (c) H-plane, unheated. (d) H-plane, heated.
VO₂ PATTERNING AND ANTENNA METALLIZATION

VO₂ patterning was done using RIE, which is a dry etching technique. The etching parameters and conditions are similar to those reported in [46] and [49]. This technique has resulted in well-defined VO₂ patches with smooth side walls for feature sizes as small as 4 μm. After the VO₂ patches are defined, openings in the SiO₂ layer over the metal pads that connect to the resistive heaters were defined using RIE as well [see Figure 18(d), inset]. Next in the fabrication process, the patterned VO₂ patches were covered with photoresist, and a Ti/Au seeding layer (40/160 nm) was deposited over the substrate. The continuity of the Ti/Au layer was verified by measuring resistance at different points on the substrate. The photoresist layer that covered the patterned VO₂ patches is removed after the seeding layer is deposited. Next, photoresist (2.3-μm thick) was spun and patterned, leaving only the antenna metallization exposed in the area defined by the antenna design; i.e., the photoresist is used as a soft mask. The outer border of the surface of the wafer was cleaned manually with acetone, removing a ring of ~2 μm of photoresist over the substrate surface. The Au layer exposed in this ring will be in contact with the electroplating sample holder. During the first 2.3 μm of Au growth, the pattern is well defined by the walls of the photoresist; but after this, the metallization grows isotropically and does not follow exactly the pattern defined on the photoresist. Given the thin VO₂ patches that separate the antenna metallization, the design and processing time had to consider side growth of the Au because, after growing thicker than the 2.3 μm of the photoresist wall, the antenna could grow over the VO₂ and create a short circuit with its extension.

After electroplating, the photoresist mask is removed and a thickness of the antenna metallization of ~4.15 μm was measured using a profilometer. The Au seeding layer (which did not grow during electroplating since it was covered with the photoresist mask) was removed with a quick dip in Au etchant (potassium iodide). The VO₂ strips were exposed during the removing of the seeding Au layer, but it was verified in previous experiments that VO₂ thin films are not attacked by Au etchant solutions. However, the removal of the Ti-seeding layer involved wet etching, and the VO₂ strips needed to be protected from this step. Thus, before removing the Ti-seeding layer through buffered oxide etching, an adhesion promoter (hexamethyldisilazane) was spun on the sample, followed by a photoresist layer that was patterned to protect the VO₂. In the final step, the photoresist layer is removed.

The result of this integration procedure is a resistive heater just underneath each strip of VO₂. The resistive heaters were tested at dc with a regulated current source. A photo of the fabricated prototype is shown in Figure 19. The dc pads and the SMA connector are also visible for scaling.

TABLE 3. DIMENSIONS FOR THE ANTENNA WITH INTEGRATED HEATERS.

<table>
<thead>
<tr>
<th>Dimension</th>
<th>Wa</th>
<th>Wb</th>
<th>Wp</th>
<th>Wf</th>
<th>Ls_hot</th>
<th>Ls_cold</th>
<th>Lf_cold</th>
<th>a</th>
<th>g</th>
<th>b</th>
</tr>
</thead>
<tbody>
<tr>
<td>Value (mm)</td>
<td>5.4</td>
<td>3.1</td>
<td>5.25</td>
<td>0.02</td>
<td>1.8</td>
<td>6.35</td>
<td>8</td>
<td>3</td>
<td>1.4</td>
<td>0.2</td>
</tr>
</tbody>
</table>
As mentioned previously, the short discontinuities of the metal layers, which are filled with VO$_2$ of relatively high permittivity value, require the thickness of the VO$_2$ and adjacent metal layers to be considered in the simulations. This is because there is a capacitive well created along the VO$_2$ patches due to coupling between the disconnected metal edges of the device, which are a few microns tall. The thin (tenths of a micrometer) VO$_2$ layer is sitting at the bottom of...
this well [see Figure 18(f)]. This capacitive well can also be observed in Figure 16(b).

**MEASUREMENT RESULTS**

The measurement setup consists of a Keithley 2400 Sourcemeter used as a regulated voltage and current source. The VO₃ transition occurred after 40 µs at a temperature of 90 °C by supplying 84-nA dc current at 20.7 V. The total power consumption was 1.74 W. Figure 19 shows also the measured heat distribution on the resistive heater at actuation. The image was taken using the OptoTherm Micro System thermal microscope and the Thermal Imaging software from OptoTherm.

Figure 20 shows the measured |S₁₁|. The resonance shifted from 9 GHz (cooled) to 11–13 GHz (heated), indicating a 33% increase. Simulated results indicate that the VO₂ modeling and the implementation of the design were successful.

**VO₂ ANTENNA RADOMES AND CLOAKING**

The metal–insulator transition of the VO₂ can find additional applications as an antenna radiation cloak or reconfigurable radome. For example, an entire sheet of transparent (insulating) VO₂ will let microwave radiation pass through it, while when heated its RF-absorbing (conductive but resistive) state will prevent radiation from passing through. When there is no need to transmit or receive, the antenna can be cloaked rapidly behind the RF-absorbing material.

An experimental investigation of the properties of VO₂ in a cloaking application was conducted next. Two Flann Microwave DP240 2–18-GHz directive horns facing each other were placed at a 2-m distance. A 2 in (5.08 cm) in diameter Al₂O₃ wafer with 200-nm-thick VO₂ deposited on it (Figure 21) was placed directly in front of one of the horns, which had an opening of 13.5 cm in diameter. The transmission between the two antennas was then measured by means of the S₂₁ parameter, removing the free-space path loss.

The VO₂ wafer was heated convectively and results were compared with the free-space scenario and with a full-metal (copper) wafer. At room temperature, the VO₂ wafer acted as a dielectric with some diffraction effects adding to the overall signal transmission compared to the attenuation of free space (i.e., without the wafer), as shown in Figure 21. When heated, the VO₂ reduced the |S₂₁| by about 4.5 dB, which is an attenuation comparable to that of a 1-in copper disk. This reduction to the transmitted signal indicates that VO₂ can be used to hide antennas and reveal them on demand, to block or allow reception of signals respectively.

The circular VO₂ “rainbows” in the 2-in wafer in Figure 21 are due to the variation in the VO₂ thickness and stoichiometry across the wafer, which varies with deposition temperature (the temperature on the wafer during deposition decreases radially from the center). Nevertheless, this change in stoichiometry is not large enough to cause a low-quality film.

**DISCUSSION**

A phase-change material (VO₂) was demonstrated to be a suitable material for use in reconfigurable antenna designs. We presented proof-of-concept reconfigurable prototypes.
for wire and aperture antennas and novel designs and methodologies, including the bandwidth reconfigurable antenna, the antenna with integrated resistive heaters, and the reconfigurable cloak. It was shown that VO₂ performs reasonably as a catalyst for reconfigurability when its phase change is thermally induced.

**TECHNOLOGY COMPARISON**

Table 4 includes a comparison of the presented VO₂ switch technology to semiconducting and MEMS switches. The comparison is based on published measured results and specification sheets available in the literature. Though not comprehensive, the comparison can serve as a reference for the feasible performance and device design space.

Advantages of using integrated heaters for the VO₂ include ease of actuation, minimal coupling from the biasing circuit for higher accuracy, and precise temperature control to record and program the different states of an antenna. Moreover, the VO₂ switch is arguably one of the smallest (shortest in length) used in a reconfigurable antenna structure. The extremely small area of the VO₂ necessary in some of the presented antennas (a few micrometers, e.g., 20-μm width by 200-nm height) allows for the heating to take place using low power. Also, the RF linearity reported for this material is excellent, as it does not rely on semiconducting components. Rather, it relies on the rearrangement of the electrons in the material lattice.

### TABLE 4. A COMPARISON OF SOME EXISTING SWITCHING TECHNOLOGIES WITH THE PROPOSED VO₂ TECHNOLOGY.

<table>
<thead>
<tr>
<th></th>
<th>p-i-n Diodes and FET Transistors*</th>
<th>MEMS Switches†</th>
<th>Proposed VO₂ Switches Technology</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Reliability</strong></td>
<td>Excellent</td>
<td>Millions to billions cycles</td>
<td>Trillions of cycles‡ (estimated)</td>
</tr>
<tr>
<td><strong>Durability/robustness</strong></td>
<td>Average (soldering)</td>
<td>Average (soldering)</td>
<td>Excellent (flush mounted; no solder) [1]</td>
</tr>
<tr>
<td><strong>Linearity/intermodulation distortion</strong></td>
<td>Nonlinear for large bandwidths</td>
<td>Excellent</td>
<td>Excellent (estimated; best reported)</td>
</tr>
<tr>
<td><strong>Actuation</strong></td>
<td>0.7 V, 1 mA; (FET: 0.3–0.4 V)</td>
<td>~15–40 V</td>
<td>&gt;10 THz‡ estimated; not yet demonstrated</td>
</tr>
<tr>
<td><strong>Highest frequency</strong></td>
<td>&lt;40 GHz</td>
<td>~40 GHz</td>
<td>&gt;10 THz‡ estimated; not yet demonstrated</td>
</tr>
<tr>
<td><strong>Switching time</strong></td>
<td>ns</td>
<td>1–300 ms</td>
<td>2 ns–40 μs (size dependent) [23]</td>
</tr>
<tr>
<td><strong>Fabrication yield</strong></td>
<td>High</td>
<td>Medium</td>
<td>High (estimated; under development)</td>
</tr>
<tr>
<td><strong>Tuning bandwidth limited</strong></td>
<td>Yes, due to biasing circuit</td>
<td>Yes, due to biasing circuit</td>
<td>No limit (thanks to remote actuation)</td>
</tr>
<tr>
<td><strong>High-resistive lines</strong></td>
<td>Not applicable</td>
<td>Required in some designs</td>
<td>Not required</td>
</tr>
<tr>
<td><strong>Power to switch</strong></td>
<td>1 mW (approximately)</td>
<td>As low as ~0.1 mW</td>
<td>1–1,000 mW (size dependent)</td>
</tr>
<tr>
<td><strong>Packaging</strong></td>
<td>Required/commercial off the shelf</td>
<td>Required</td>
<td>Not required‡</td>
</tr>
<tr>
<td><strong>Hot switching</strong></td>
<td>Yes (diodes); No (FET)</td>
<td>No</td>
<td>Yes</td>
</tr>
<tr>
<td><strong>Size</strong></td>
<td>~2 × 2 mm</td>
<td>~150 × 350 μm</td>
<td>~20 × 20 μm² to 1,000 × 1,000 μm²; varies</td>
</tr>
<tr>
<td><strong>Shunt configuration</strong></td>
<td><strong>IL&lt;sub&gt;ON&lt;/sub&gt; &lt; 0.2 dB @ 0.5 GHz, 1.2 dB @ 5 GHz, ISO&lt;sub&gt;OFF&lt;/sub&gt; ~ 30 to 1 dB</strong></td>
<td><strong>IL&lt;sub&gt;ON&lt;/sub&gt; ~ 0.6 dB, ISO&lt;sub&gt;OFF&lt;/sub&gt; &gt; 20 dB</strong></td>
<td><strong>IL&lt;sub&gt;ON&lt;/sub&gt; &lt; 0.3 dB (estimate), ISO&lt;sub&gt;OFF&lt;/sub&gt; &gt; 25 dB</strong></td>
</tr>
<tr>
<td><strong>Series configuration</strong></td>
<td><strong>IL&lt;sub&gt;ON&lt;/sub&gt; &lt; 0.1 dB @ 0.5 GHz, &gt;5 dB @ 5 GHz, ISO&lt;sub&gt;OFF&lt;/sub&gt; ~ 40 to 3 dB</strong></td>
<td><strong>IL&lt;sub&gt;ON&lt;/sub&gt; &lt; 0.3 dB, ISO&lt;sub&gt;OFF&lt;/sub&gt; &lt; −15 dB</strong></td>
<td><strong>IL&lt;sub&gt;ON&lt;/sub&gt; &lt; 1 dB (reducible), ISO&lt;sub&gt;OFF&lt;/sub&gt; &lt; −20 dB</strong></td>
</tr>
</tbody>
</table>

IL: insertion loss; ISO: isolation.


‡As long as the VO₂ is not operated in extremely harsh environments (e.g., above 250 °C, in an oxidizing atmosphere, or in any acidic or basic solutions), it should sustain that many actuation cycles.

§As long as the VO₂ is not taken to extreme environments.
ACTUATION MECHANISM
The variety of methods to induce this phase change (thermal via conductive heating, thermal via Joule heating, photothermal, voltage difference, remote optical excitation via laser) eliminates the need for wired biasing. Because the actuation mechanism of the VO₂ is decoupled from the antenna, the antenna engineer has an additional degree of freedom, permitting reconfigurability without the limitations imposed by traditional electrically connected biasing circuits. This enables large structures, such as reconfigurable arrays and reflectarrays with hundreds of elements, to be realized. The remote actuation capability of VO₂ (e.g., through the heat of a laser) further removes completely the need for any form of biasing network and enables new designs that are optically activated, dynamically reconfigurable, and able to be actuated extremely fast for real-time communication, surveillance, sensing, and security applications.

FABRICATION
The complexity of fabrication may impose limitations on the substrates used. However, fabrication should be simpler than for MEMS as it does not involve suspended cantilever photolithography [13], [50]. Cost will highly depend on the substrate (e.g., sapphire or quartz). For the switches in this article, at the time of writing, cost was estimated at US$0.2 to US$0.5 per mm² with a time to fabrication of one day in a research laboratory, allowing designs with resolution down to 4 μm or lower.

TRANSITION TIME LIMIT
The implementation of integrated resistive heaters on wafer allows for faster and seamless electronic actuation of the VO₂. Reconfiguration speed for RF applications is approximately 10 μs, which is on a par with MEMS. Transition time, however, relates to the volume of the VO₂ that needs to be heated. Transitions with rise times as fast as 2 ns have been reported [51] when the VO₂ was grown directly on the tips of metal electrodes spaced a few hundreds of nanometers apart. The Joule heating is expected to facilitate fast actuation speeds as long as the area of the VO₂ remains relatively small.

PACKAGING
VO₂ does not require packaging in nonextreme environments. Also, the hysteresis of the transition allows for small temperature fluctuations without affecting device performance. All measurements were taken in a controlled laboratory environment with relatively stable temperature, and there was no need for packaging. Also, the switch was robust to human touch. The system can be sensitive to random large temperature fluctuations in the environment, especially during the phase-transition region. Technically, if we want the VO₂ to be robust against changes of temperature in the environment, then we need to either include a control system to the circuitry used to actuate the VO₂ or some form of packaging. With rapid heating, cooling, and feedback mechanisms, the device temperature could be stabilized even in fluctuating temperature conditions and be made suitable for outdoor terrestrial and space environments (e.g., satellite antennas or mobile phone base stations).

ROBUSTNESS
The fabricated integrated prototypes are very robust, and device lifetime is expected to be very long since no moving parts or soldering is required. Weight and size are estimated to be the smallest among all existing technologies (p-i-n diodes, varactors, FET transistors, and MEMS), most of which come in a package. The low transition temperature (68 °C) ensures no damage or significant expansion due to the conduction of heat to nearby cables and circuits. Convective heating even up to 80 °C conforms to all standard coaxial cables (e.g., RG-58, RG-59 [52], [53]), military cables (they are rated up to 105 °C [54]), SMA connectors (rated to 165 °C [55]), Polytetrafluoroethylene Teflon insulation of coaxial cables (rated to 160 °C [56]), most common dielectrics, paper, and off-the-shelf components, such as p-i-n diodes (rated to 125 °C) [57]. Moreover, localized Joule heating does not propagate to damage other parts of the antenna and add noise directly into the receiver.

POWER CONSUMPTION
On the other hand, power consumption is higher than it is for most other technologies, with a 1–2-W (20 V, 80 mA) estimated requirement for actuation, mainly due to the high current needed to increase the temperature of the VO₂.

CONCLUSIONS
The fabrication and integration challenges of VO₂ with a focus on reconfigurable antennas and microwave devices were presented. Results clearly demonstrate that VO₂ can be used for more than RF switches, while there is space and need for improvements. There are multiple dimensions in this tradeoff space of reconfigurable components using VO₂. VO₂ is a promising material that enables new components, new designs, and new fundamental building blocks in RF design. Further research for loss reduction and accurate resistivity control can make this a very promising material for wideband RF applications and can lead to new designs that fully use the unique capabilities of the VO₂-integrated thin-film switches that may replace other off-the-shelf components. In addition, the implications of the measured hysteresis curve can be explored to enable programmable devices and lead to other exciting discoveries. This article is supported by online multimedia material in IEEE DataPort [48].

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